



PRELIMINARY SPECIFICATION

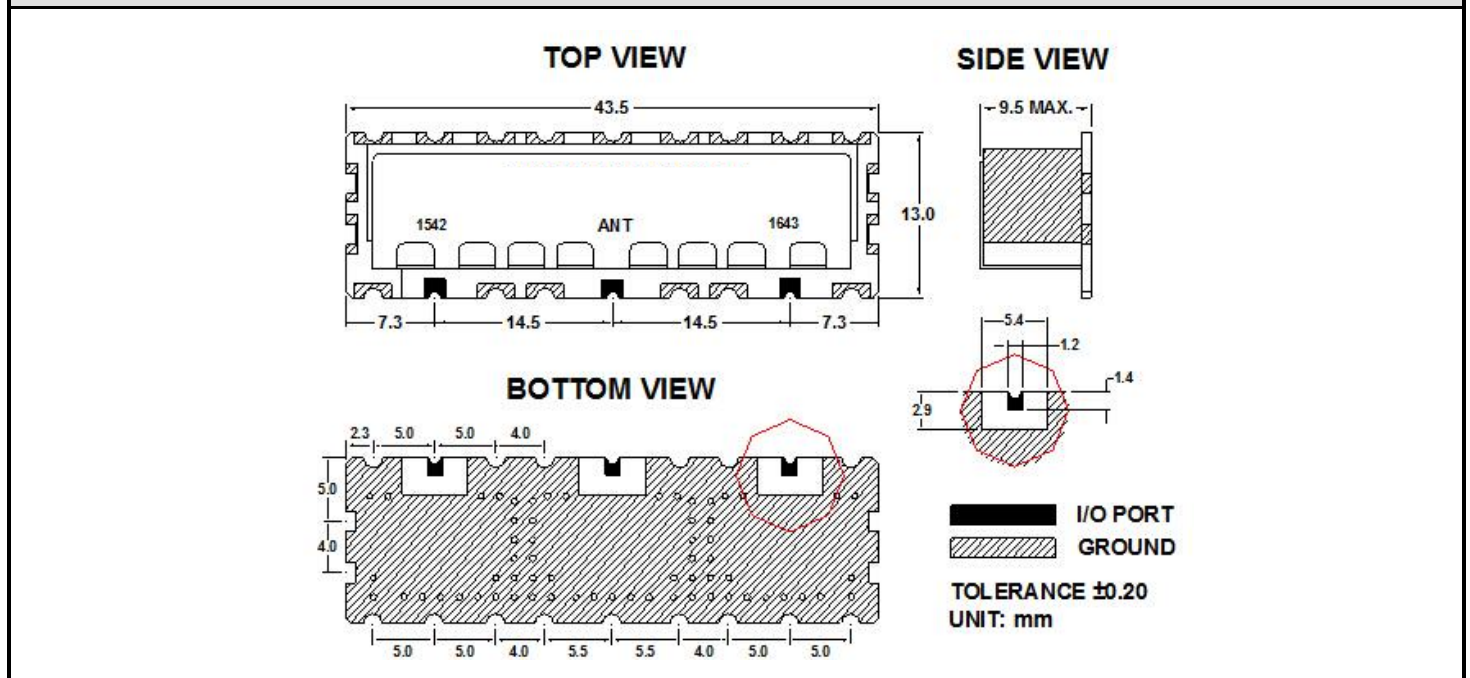
Part No.: _____
 Customer: _____
 Date: **2015-06-12**

Written by	Checked by	Approval

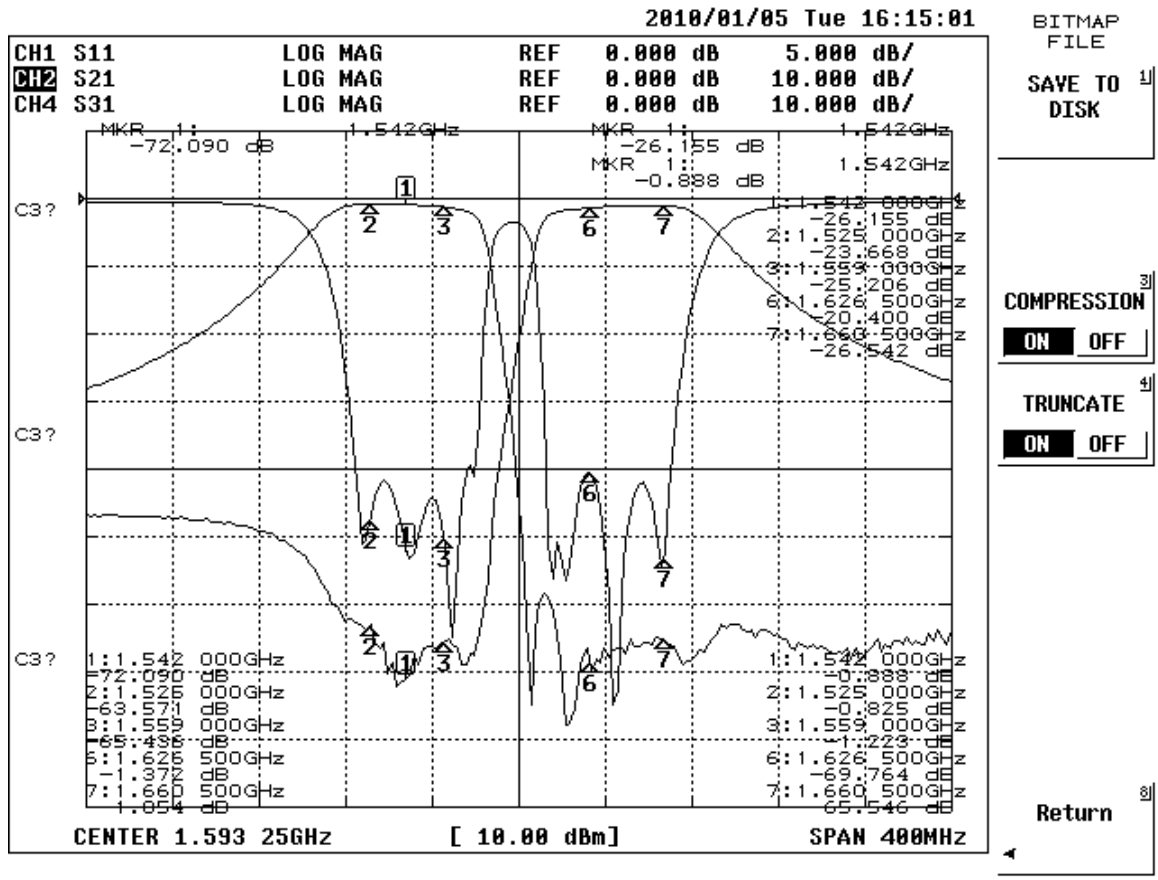
ELECTRICAL SPECIFICATIONS

ITEM	SPEC	UNIT
1	Center Frequency [fo]	1542.0 1643.5
2	Bandwidth [BW]	fo±17.0 [1525.0-1559.0] fo±17.0 [1626.5-1660.5]
2	Insertion Loss at BW	1.8 1.8 dB max.
4	Ripple in BW	0.5 0.5 dB max.
5	V.S.W.R in BW	2.0 2.0 max.
6	Attenuation [Absolute Value]	64.0 dB min. @ 【1626.5-1559.0】 59.0 dB min. @ 【1525.0-1660.5】
7	In/Out Impedance	50 Ω
8	Operation Temperature Range	-40~+85°C °C
9	Return Loss in BW	
10	Group Delay Variation	
11	Input Power	8.0 W

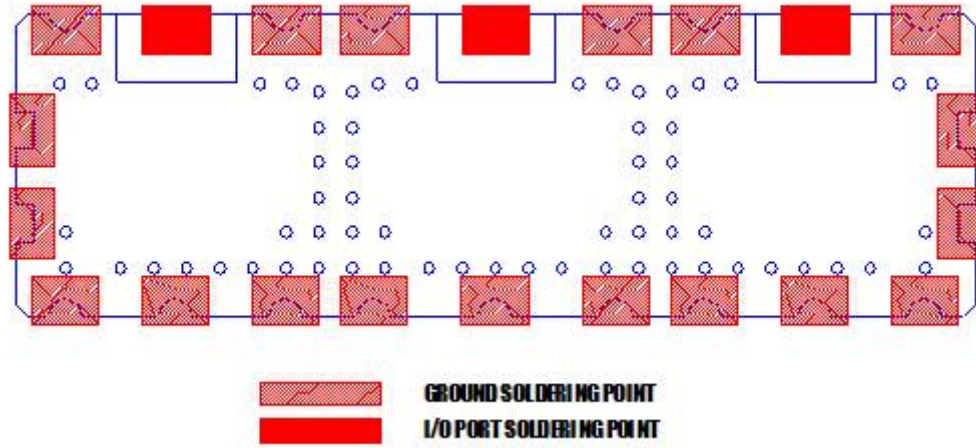
MECHANICAL SPECIFICATION



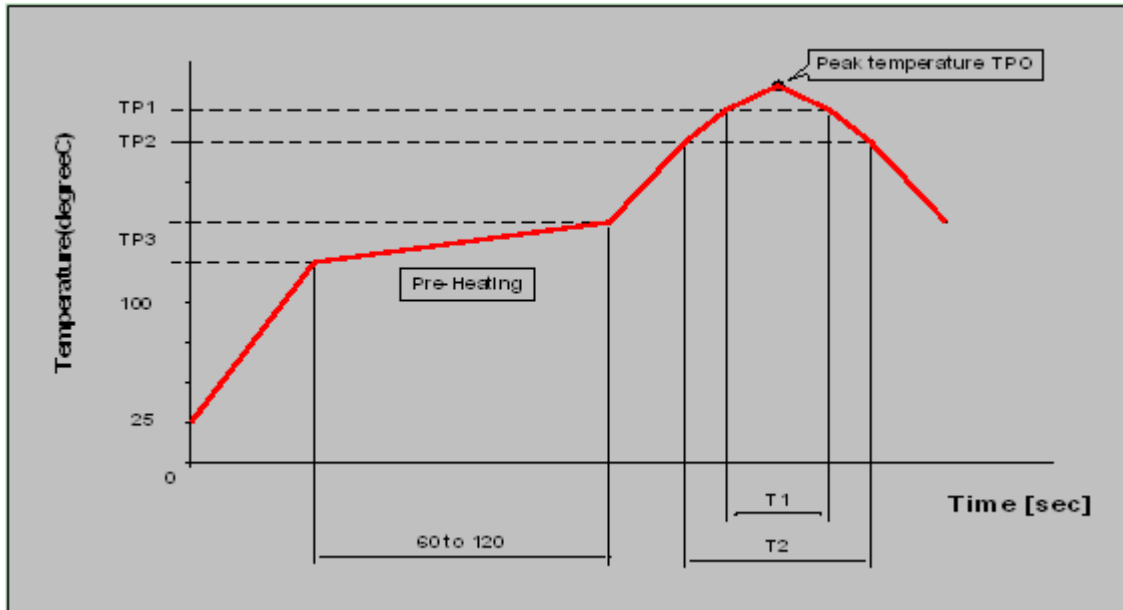
PERFORMANCE



RECOMMENDED PC BOARD PATTERN



SOLDERING CONDITION



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (°C)	TP1 (°C)	T1 (s)	TP2 (°C)	T2 (s)	TP3 (°C)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	—	—	150 to 130
Test condition of reflow test resistance	260+5/-0	240	20	220	70	150 to 130